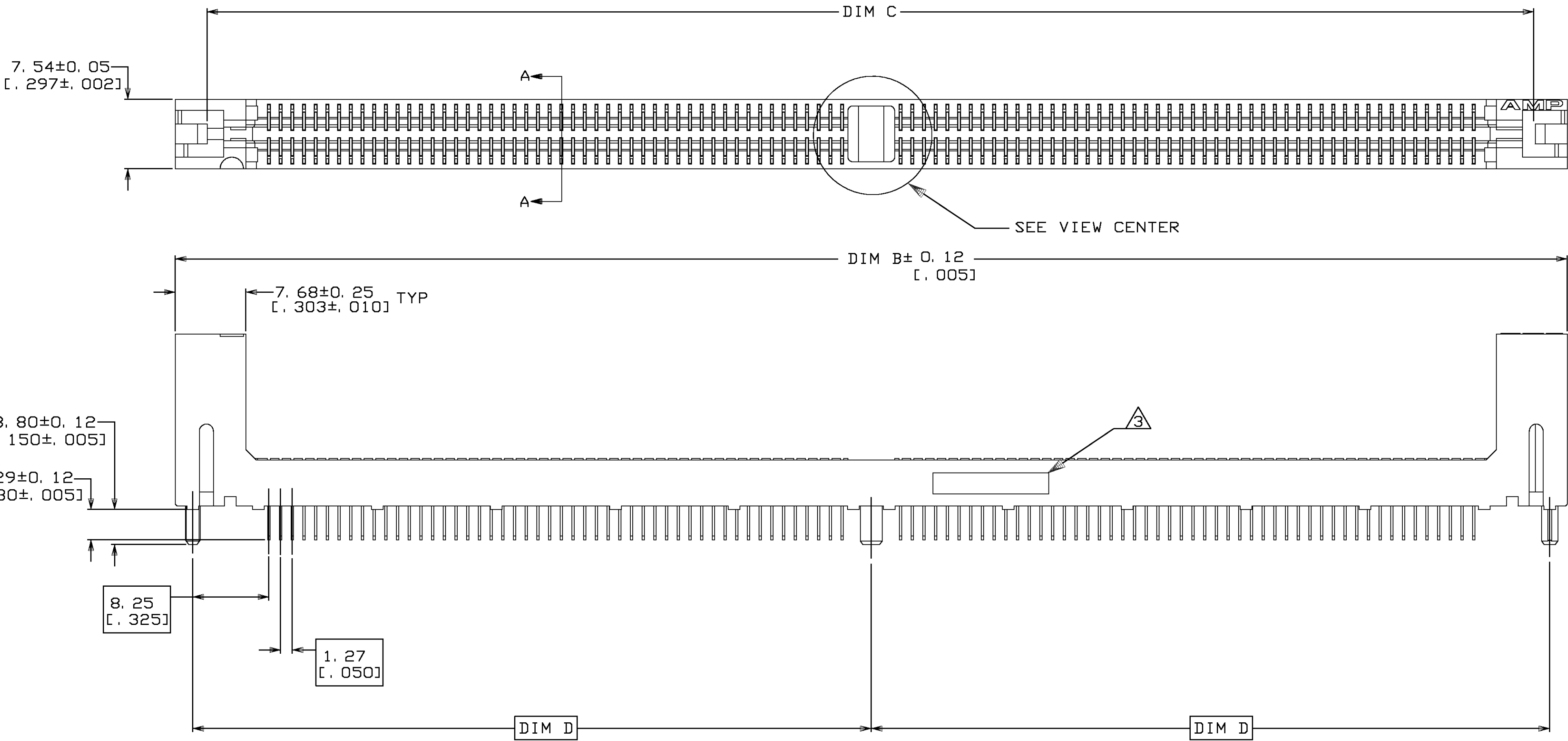
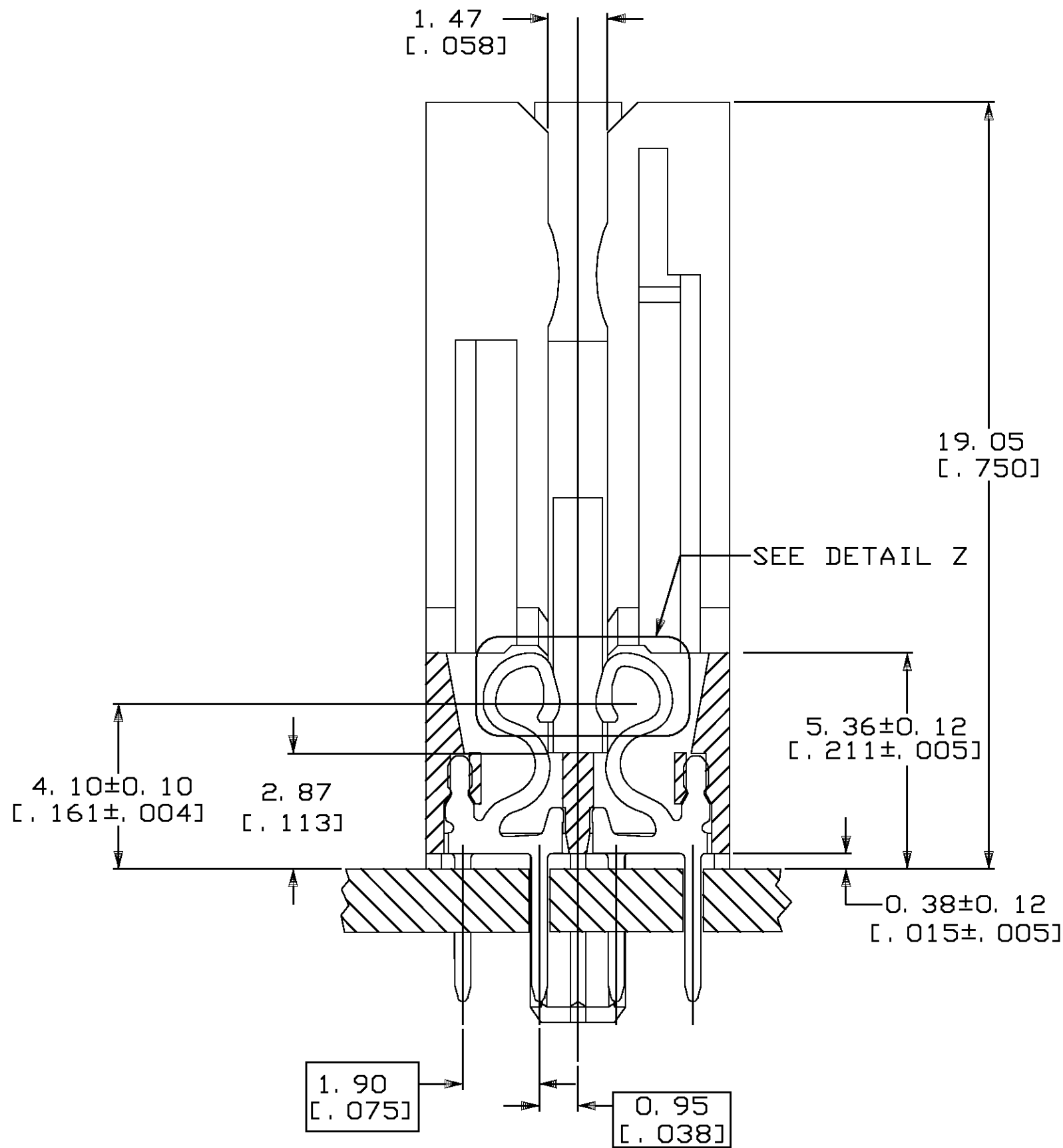
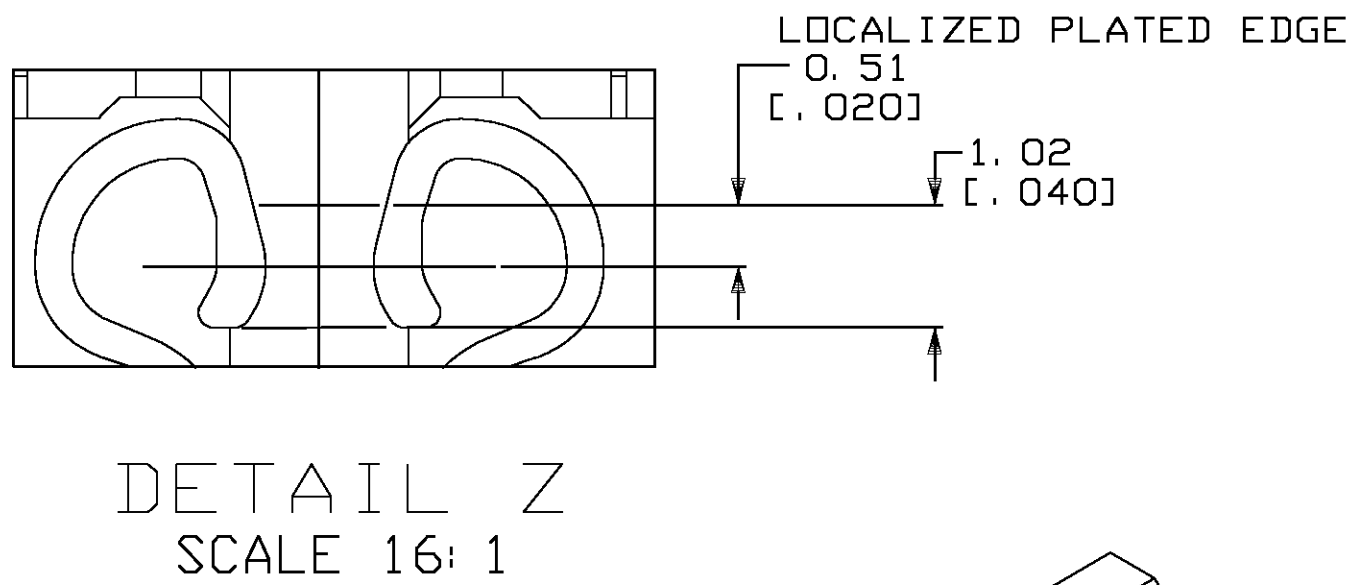
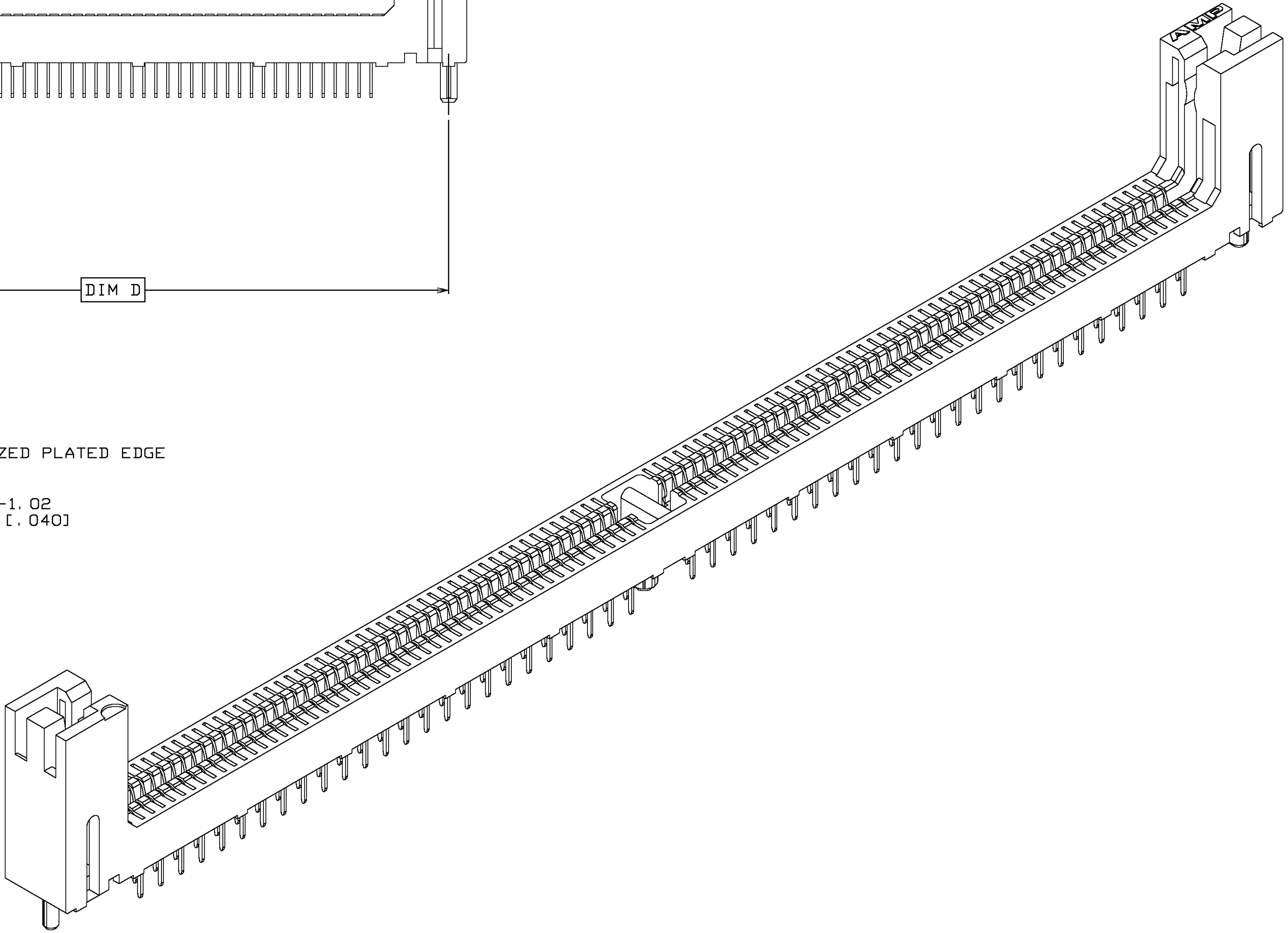


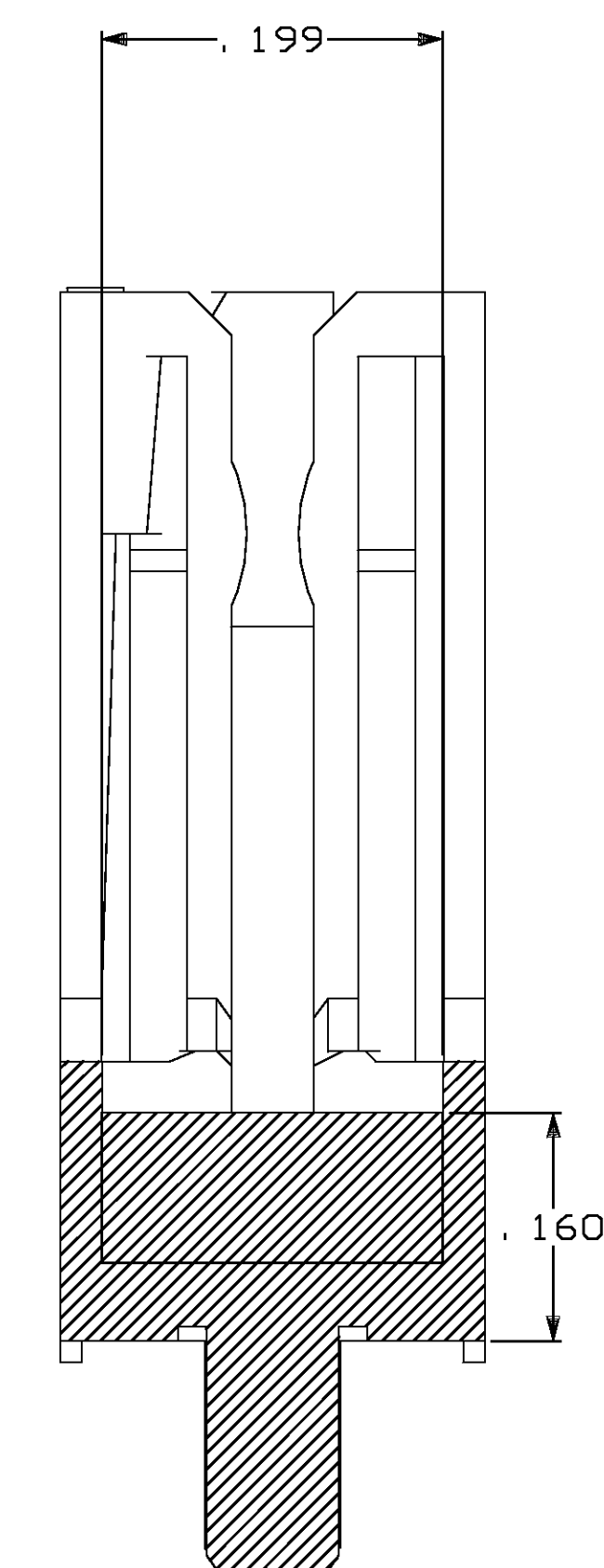
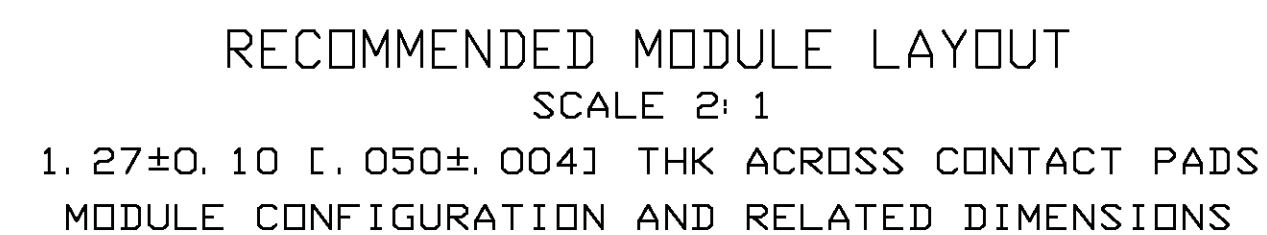
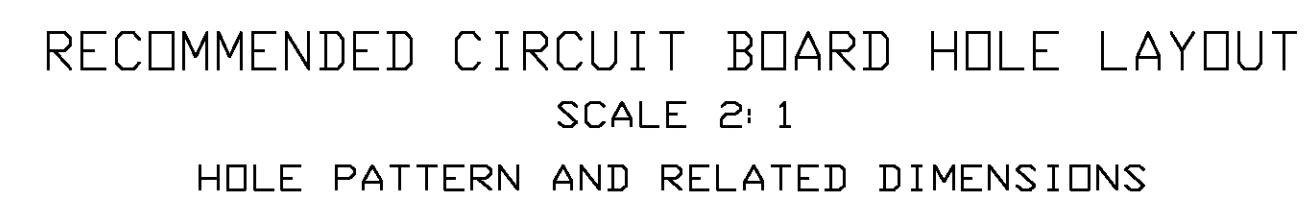
LOC	DIST	REVISIONS					
GP	00	P	LTR	DESCRIPTION	DATE	DWN	APVD
			B	REV PER EC 0S11-0145-04	09JUL04	BC	DS



1. PLATING- CONTACT MATING AREA, 0.00076 [.000030] MIN THK GOLD ON MATING EDGE OF SOLDER TAIL, 0.00381 [.000150] MIN THK TIN-LEAD UNDERPLATE, 0.00127 [.000050] MIN THK NICKEL OVER ENTIRE CONTACT. BASE MATERIAL: PHOSPHOR BRONZE.
2. PLASTIC INSULATOR MATERIAL, GLASS FILLED, HIGH TEMPERATURE NYLON: COLOR, BLACK.
3. DATE CODE INFORMATION (YEAR, WEEK, DAY), LOCATED APPROXIMATELY AS SHOWN.
4. FOR OPTIMAL PERFORMANCE, CONTACT PAD PLATING SHOULD BE SMOOTH AND FLAT. COPPER CONTACT PADS ARE TO BE OVERPLATED WITH 0.00127 [.000050] MIN THK NICKEL FOLLOWED WITH 0.00076 [.000030] MIN THK HARD GOLD PLATING. LEADING EDGES OF MODULE SHOULD BE FREE OF SHARP CORNERS.
5. SOLDER TAIL X-SECTION 0.40 x 0.25 [.016 x .010]



130.81[5.150]	143.51[5.650]	73.66[2.900]	143.76[5.660]	151.13[5.950]	136.75[5.384]	100	200	390374-1
DIM F	DIM E	DIM D	DIM C	DIM B	DIM A	POSITION	NO. OF INPUT/OUTPUT	PART NO.
				THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN J. BURWELL 13APROD		
				DIMENSIONS: MM		Tyco Electronics Corporation		
				TOLERANCES UNLESS OTHERWISE SPECIFIED:		D. SHIRLING 13APROD		
				0 PLC ± -		NAME		
				1 PLC ± -		APVD D. SHIRLING 13APROD		
				2 PLC ± -		PRODUCT SPEC		
				3 PLC ± -		STANDARD CARD GUIDES, SINGLE ROW, NO EXTRACTORS		
				4 PLC ± -		1.27 [.050] (FULL WIPE)		
				ANGLES ± -		APPLICATION SPEC		
				FINISH ± 0.08 [.003]		SIZE CAGE CODE DRAWING NO RESTRICTED TO		
				MATERIAL		A1 00779 ©=390374		
				WEIGHT		CUSTOMER DRAWING		
				FINISH		SCALE 1:1 SHEET 1 OF 2 REV B		



Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[TE Connectivity:](#)

[390374-1](#)